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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	16
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	224 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f628at-e-ss

PIC16F627A/628A/648A

18-pin Flash-Based, 8-Bit CMOS Microcontrollers with nanoWatt Technology

High-Performance RISC CPU:

- Operating speeds from DC – 20 MHz
- Interrupt capability
- 8-level deep hardware stack
- Direct, Indirect and Relative Addressing modes
- 35 single-word instructions:
  - All instructions single cycle except branches

Special Microcontroller Features:

- Internal and external oscillator options:
  - Precision internal 4 MHz oscillator factory calibrated to ±1%
  - Low-power internal 48 kHz oscillator
  - External Oscillator support for crystals and resonators
- Power-saving Sleep mode
- Programmable weak pull-ups on PORTB
- Multiplexed Master Clear/Input-pin
- Watchdog Timer with independent oscillator for reliable operation
- Low-voltage programming
- In-Circuit Serial Programming™ (via two pins)
- Programmable code protection
- Brown-out Reset
- Power-on Reset
- Power-up Timer and Oscillator Start-up Timer
- Wide operating voltage range (2.0-5.5V)
- Industrial and extended temperature range
- High-Endurance Flash/EEPROM cell:
  - 100,000 write Flash endurance
  - 1,000,000 write EEPROM endurance
  - 40 year data retention

Low-Power Features:

- Standby Current:
  - 100 nA @ 2.0V, typical
- Operating Current:
  - 12 μA @ 32 kHz, 2.0V, typical
  - 120 μA @ 1 MHz, 2.0V, typical
- Watchdog Timer Current:
  - 1 μA @ 2.0V, typical
- Timer1 Oscillator Current:
  - 1.2 μA @ 32 kHz, 2.0V, typical
- Dual-speed Internal Oscillator:
  - Run-time selectable between 4 MHz and 48 kHz
  - 4 μs wake-up from Sleep, 3.0V, typical

Peripheral Features:

- 16 I/O pins with individual direction control
- High current sink/source for direct LED drive
- Analog comparator module with:
  - Two analog comparators
  - Programmable on-chip voltage reference (V_{REF}) module
  - Selectable internal or external reference
  - Comparator outputs are externally accessible
- Timer0: 8-bit timer/counter with 8-bit programmable prescaler
- Timer1: 16-bit timer/counter with external crystal/clock capability
- Timer2: 8-bit timer/counter with 8-bit period register, prescaler and postscaler
- Capture, Compare, PWM module:
  - 16-bit Capture/Compare
  - 10-bit PWM
- Addressable Universal Synchronous/Asynchronous Receiver/Transmitter USART/SCI

Device	Program Memory	Data Memory		I/O	CCP (PWM)	USART	Comparators	Timers 8/16-bit
	Flash (words)	SRAM (bytes)	EEPROM (bytes)					
PIC16F627A	1024	224	128	16	1	Y	2	2/1
PIC16F628A	2048	224	128	16	1	Y	2	2/1
PIC16F648A	4096	256	256	16	1	Y	2	2/1

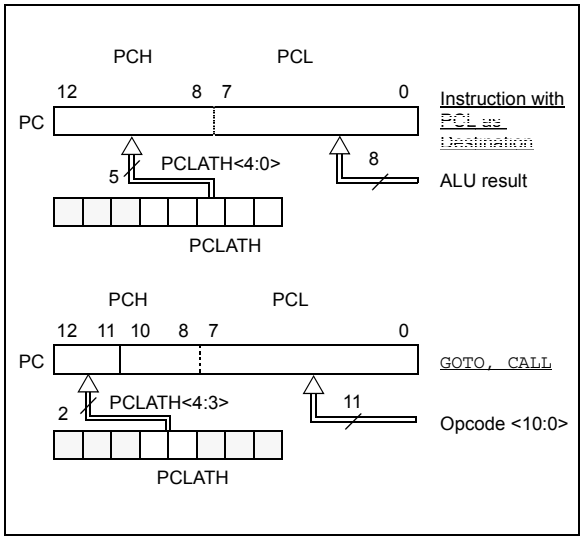
NOTES:

NOTES:

4.3 PCL and PCLATH

The Program Counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<12:8>) is not directly readable or writable and comes from PCLATH. On any Reset, the PC is cleared. Figure 4-4 shows the two situations for loading the PC. The upper example in Figure 4-4 shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in Figure 4-4 shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> → PCH).

FIGURE 4-4: LOADING OF PC IN DIFFERENT SITUATIONS



4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block). Refer to the Application Note AN556 "*Implementing a Table Read*" (DS00556).

4.3.2 STACK

The PIC16F627A/628A/648A family has an 8-level deep x 13-bit wide hardware stack (Figure 4-1). The stack space is not part of either program or data space and the Stack Pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth PUSH overwrites the value that was stored from the first PUSH. The tenth PUSH overwrites the second PUSH (and so on).

Note 1: There are no Status bits to indicate stack overflow or stack underflow conditions.

2: There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions, or the vectoring to an interrupt address.

4.4 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses data pointed to by the File Select Register (FSR). Reading INDF itself indirectly will produce 00h. Writing to the INDF register indirectly results in a no-operation (although Status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-5.

A simple program to clear RAM location 20h-2Fh using indirect addressing is shown in Example 4-1.

EXAMPLE 4-1: INDIRECT ADDRESSING

```
        MOVLW   0x20    ;initialize pointer
        MOVWF   FSR     ;to RAM
NEXT    CLRF    INDF    ;clear INDF register
        INCF    FSR     ;inc pointer
        BTFSS   FSR,4   ;all done?
        GOTO    NEXT    ;no clear next
                        ;yes continue
```

TABLE 5-1: PORTA FUNCTIONS

Name	Function	Input Type	Output Type	Description
RA0/AN0	RA0	ST	CMOS	Bidirectional I/O port
	AN0	AN	—	Analog comparator input
RA1/AN1	RA1	ST	CMOS	Bidirectional I/O port
	AN1	AN	—	Analog comparator input
RA2/AN2/VREF	RA2	ST	CMOS	Bidirectional I/O port
	AN2	AN	—	Analog comparator input
	VREF	—	AN	VREF output
RA3/AN3/CMP1	RA3	ST	CMOS	Bidirectional I/O port
	AN3	AN	—	Analog comparator input
	CMP1	—	CMOS	Comparator 1 output
RA4/T0CKI/CMP2	RA4	ST	OD	Bidirectional I/O port. Output is open drain type.
	T0CKI	ST	—	External clock input for TMR0 or comparator output
	CMP2	—	OD	Comparator 2 output
RA5/$\overline{\text{MCLR}}$/VPP	RA5	ST	—	Input port
	$\overline{\text{MCLR}}$	ST	—	Master clear. When configured as $\overline{\text{MCLR}}$, this pin is an active low Reset to the device. Voltage on $\overline{\text{MCLR}}$/VPP must not exceed VDD during normal device operation.
	VPP	HV	—	Programming voltage input
RA6/OSC2/CLKOUT	RA6	ST	CMOS	Bidirectional I/O port
	OSC2	—	XTAL	Oscillator crystal output. Connects to crystal resonator in Crystal Oscillator mode.
	CLKOUT	—	CMOS	In RC or INTOSC mode. OSC2 pin can output CLKOUT, which has 1/4 the frequency of OSC1.
RA7/OSC1/CLKIN	RA7	ST	CMOS	Bidirectional I/O port
	OSC1	XTAL	—	Oscillator crystal input. Connects to crystal resonator in Crystal Oscillator mode.
	CLKIN	ST	—	External clock source input. RC biasing pin.

Legend: O = Output — = Not used TTL = TTL Input CMOS = CMOS Output I = Input OD = Open Drain Output P = Power ST = Schmitt Trigger Input AN = Analog

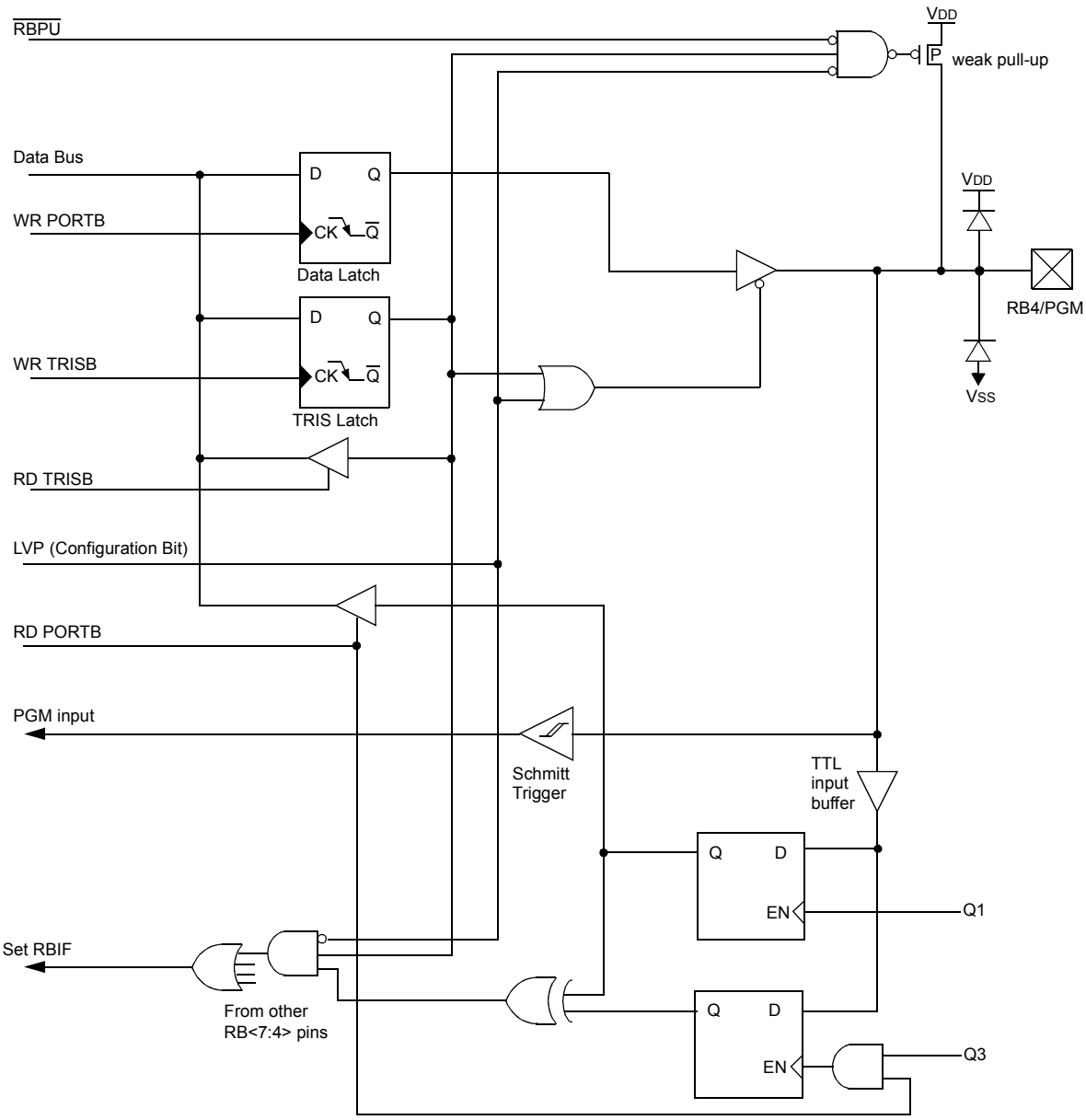
TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other Resets
05h	PORTA	RA7	RA6	RA5(1)	RA4	RA3	RA2	RA1	RA0	xxxx 0000	qqqu 0000
85h	TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1111 1111	1111 1111
1Fh	CMCON	C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0	0000 0000	0000 0000
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000

Legend: - = Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition. Shaded cells are not used for PORTA.

Note 1: MCLRE configuration bit sets RA5 functionality.

FIGURE 5-12: BLOCK DIAGRAM OF RB4/PGM PIN



Note: The low-voltage programming disables the interrupt-on-change and the weak pull-ups on RB4.

10.0 COMPARATOR MODULE

The comparator module contains two analog comparators. The inputs to the comparators are multiplexed with the RA0 through RA3 pins. The on-chip Voltage Reference (**Section 11.0 "Voltage Reference Module"**) can also be an input to the comparators.

The CMCON register, shown in Register 10-1, controls the comparator input and output multiplexers. A block diagram of the comparator is shown in Figure 10-1.

REGISTER 10-1: CMCON – COMPARATOR CONFIGURATION REGISTER (ADDRESS: 01Fh)

R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
C2OUT	C1OUT	C2INV	C1INV	CIS	CM2	CM1	CM0
bit 7							bit 0

bit 7 **C2OUT**: Comparator 2 Output bit

When C2INV = 0:
1 = C2 VIN+ > C2 VIN-
0 = C2 VIN+ < C2 VIN-

When C2INV = 1:
1 = C2 VIN+ < C2 VIN-
0 = C2 VIN+ > C2 VIN-

bit 6 **C1OUT**: Comparator 1 Output bit

When C1INV = 0:
1 = C1 VIN+ > C1 VIN-
0 = C1 VIN+ < C1 VIN-

When C1INV = 1:
1 = C1 VIN+ < C1 VIN-
0 = C1 VIN+ > C1 VIN-

bit 5 **C2INV**: Comparator 2 Output Inversion bit
1 = C2 Output inverted
0 = C2 Output not inverted

bit 4 **C1INV**: Comparator 1 Output Inversion bit
1 = C1 Output inverted
0 = C1 Output not inverted

bit 3 **CIS**: Comparator Input Switch bit

When CM<2:0>: = 001
Then:
1 = C1 VIN- connects to RA3
0 = C1 VIN- connects to RA0

When CM<2:0> = 010
Then:
1 = C1 VIN- connects to RA3
C2 VIN- connects to RA2
0 = C1 VIN- connects to RA0
C2 VIN- connects to RA1

bit 2-0 **CM<2:0>**: Comparator Mode bits
Figure 10-1 shows the comparator modes and CM<2:0> bit settings

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

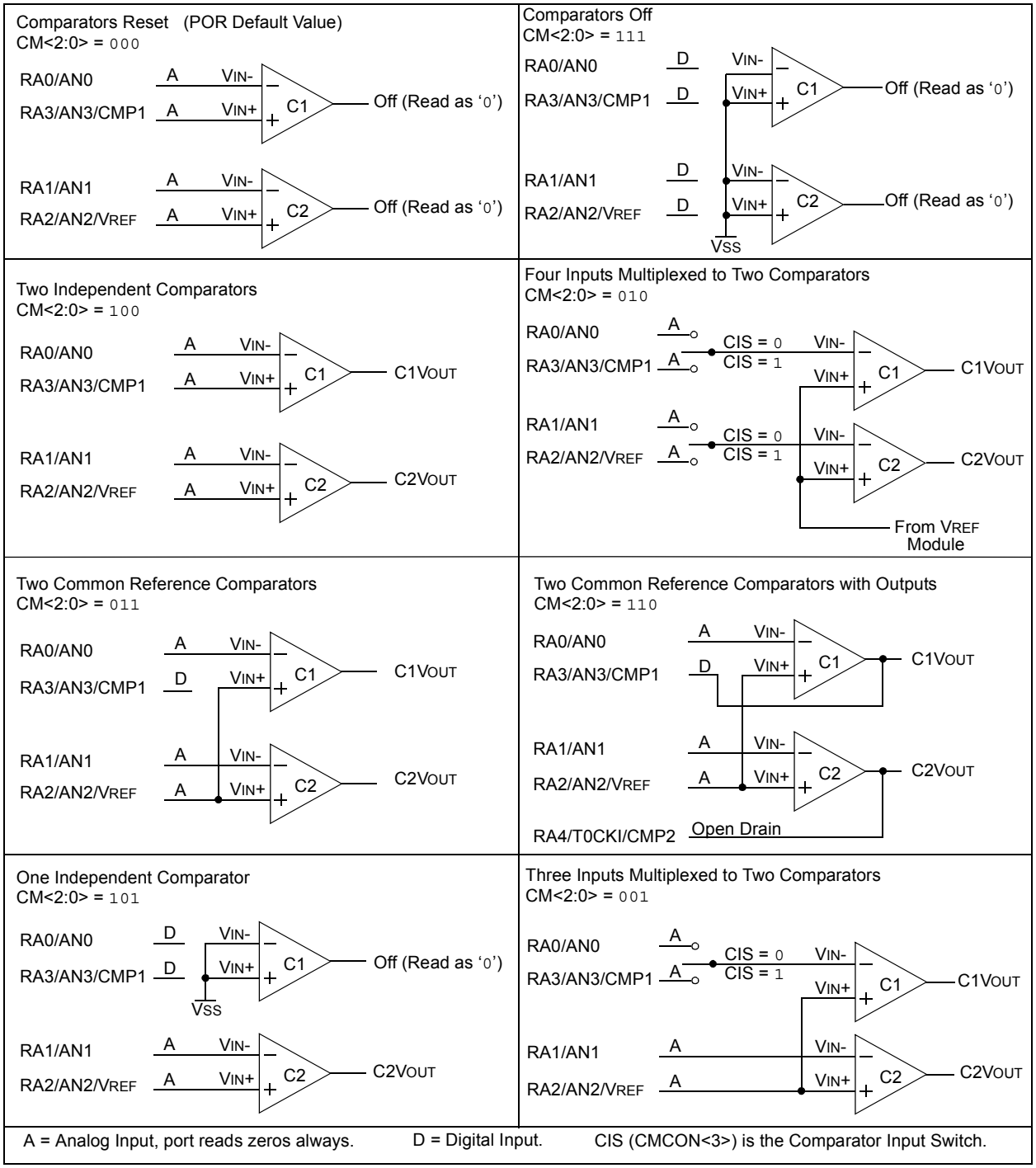
10.1 Comparator Configuration

There are eight modes of operation for the comparators. The CMCON register is used to select the mode. Figure 10-1 shows the eight possible modes. The TRISA register controls the data direction of the comparator pins for each mode.

If the Comparator mode is changed, the comparator output level may not be valid for the specified mode change delay shown in Table 17-2.

Note 1:	Comparator interrupts should be disabled during a Comparator mode change, otherwise a false interrupt may occur.
2:	Comparators can have an inverted output. See Figure 10-1.

FIGURE 10-1: COMPARATOR I/O OPERATING MODES



A = Analog Input, port reads zeros always. D = Digital Input. CIS (CMCON<3>) is the Comparator Input Switch.

12.1 USART Baud Rate Generator (BRG)

The BRG supports both the Asynchronous and Synchronous modes of the USART. It is a dedicated 8-bit baud rate generator. The SPBRG register controls the period of a free running 8-bit timer. In Asynchronous mode, bit BRGH (TXSTA<2>) also controls the baud rate. In Synchronous mode, bit BRGH is ignored. Table 12-1 shows the formula for computation of the baud rate for different USART modes, which only apply in Master mode (internal clock).

Given the desired baud rate and FOSC, the nearest integer value for the SPBRG register can be calculated using the formula in Table 12-1. From this, the error in baud rate can be determined.

Example 12-1 shows the calculation of the baud rate error for the following conditions:

FOSC = 16 MHz

Desired Baud Rate = 9600

BRGH = 0

SYNC = 0

EQUATION 12-1: CALCULATING BAUD RATE ERROR

$$Desired\ Baud\ Rate = \frac{Fosc}{64(x+1)}$$

$$9600 = \frac{16000000}{64(x+1)}$$

$$x = 25.042$$

$$Calculated\ Baud\ Rate = \frac{16000000}{64(25+1)} = 9615$$

$$Error = \frac{(Calculated\ Baud\ Rate - Desired\ Baud\ Rate)}{Desired\ Baud\ Rate}$$

$$= \frac{9615 - 9600}{9600} = 0.16\%$$

It may be advantageous to use the high baud rate (BRGH = 1) even for slower baud clocks. This is because the FOSC/(16(X + 1)) equation can reduce the baud rate error in some cases.

Writing a new value to the SPBRG register causes the BRG timer to be reset (or cleared) and ensures the BRG does not wait for a timer overflow before outputting the new baud rate.

The data on the RB1/RX/DT pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin.

TABLE 12-1: BAUD RATE FORMULA

SYNC	BRGH = 0 (Low Speed)	BRGH = 1 (High Speed)
0	(Asynchronous) Baud Rate = FOSC/(64(X+1))	Baud Rate = FOSC/(16(X+1))
1	(Synchronous) Baud Rate = FOSC/(4(X+1))	NA

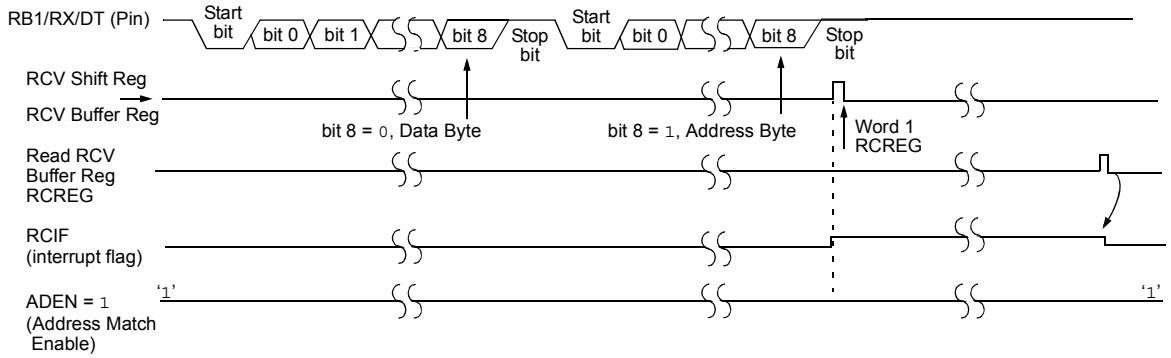
Legend: X = value in SPBRG (0 to 255)

TABLE 12-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on all other Resets
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
18h	RCSTA	SPEN	RX9	SREN	CREN	ADEN	FERR	OERR	RX9D	0000 000x	0000 000x
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

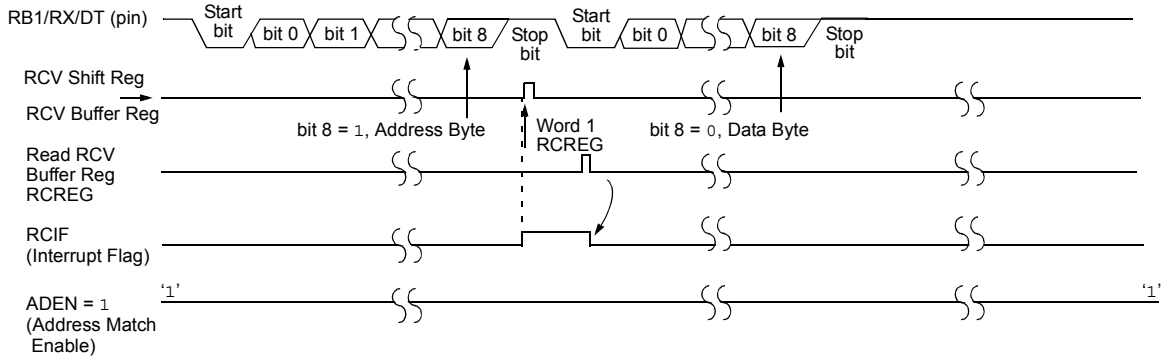
Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for the BRG.

FIGURE 12-5: ASYNCHRONOUS RECEPTION WITH ADDRESS DETECT



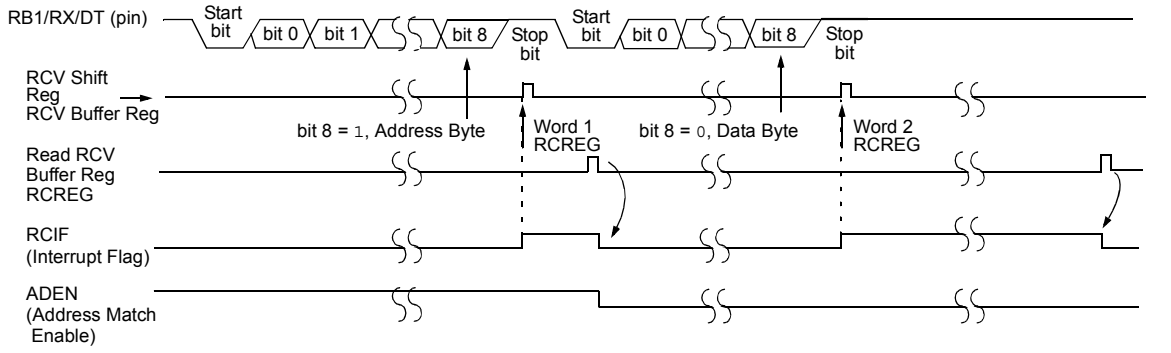
Note: This timing diagram shows a data byte followed by an address byte. The data byte is not read into the RCREG (Receive Buffer) because ADEN = 1 and bit 8 = 0.

FIGURE 12-6: ASYNCHRONOUS RECEPTION WITH ADDRESS BYTE FIRST



Note: This timing diagram shows an address byte followed by an data byte. The data byte is not read into the RCREG (receive buffer) because ADEN was not updated (still = 1) and bit 8 = 0.

FIGURE 12-7: ASYNCHRONOUS RECEPTION WITH ADDRESS BYTE FIRST FOLLOWED BY VALID DATA BYTE



Note: This timing diagram shows an address byte followed by an data byte. The data byte is read into the RCREG (Receive Buffer) because ADEN was updated after an address match, and was cleared to a '0', so the contents of the Receive Shift Register (RSR) are read into the Receive Buffer regardless of the value of bit 8.

13.0 DATA EEPROM MEMORY

The EEPROM data memory is readable and writable during normal operation (full VDD range). This memory is not directly mapped in the register file space. Instead it is indirectly addressed through the Special Function Registers (SFRs). There are four SFRs used to read and write this memory. These registers are:

- EECON1
- EECON2 (Not a physically implemented register)
- EEDATA
- EEADR

EEDATA holds the 8-bit data for read/write and EEADR holds the address of the EEPROM location being accessed. PIC16F627A/628A devices have 128 bytes of data EEPROM with an address range from 0h to 7Fh. The PIC16F648A device has 256 bytes of data EEPROM with an address range from 0h to FFh.

The EEPROM data memory allows byte read and write. A byte write automatically erases the location and writes the new data (erase before write). The EEPROM data memory is rated for high erase/write cycles. The write time is controlled by an on-chip timer. The write time will vary with voltage and temperature, as well as from chip-to-chip. Please refer to AC specifications for exact limits.

When the device is code-protected, the CPU can continue to read and write the data EEPROM memory. A device programmer can no longer access this memory.

Additional information on the data EEPROM is available in the *PIC® Mid-Range Reference Manual* (DS33023).

REGISTER 13-1: EEDATA – EEPROM DATA REGISTER (ADDRESS: 9Ah)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EEDAT7	EEDAT6	EEDAT5	EEDAT4	EEDAT3	EEDAT2	EEDAT1	EEDAT0
bit 7							bit 0

bit 7-0 **EEDATn**: Byte value to Write to or Read from data EEPROM memory location.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

REGISTER 13-2: EEADR – EEPROM ADDRESS REGISTER (ADDRESS: 9Bh)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EADR7	EADR6	EADR5	EADR4	EADR3	EADR2	EADR1	EADR0
bit 7							bit 0

bit 7 **PIC16F627A/628A**
Unimplemented Address: Must be set to ‘0’

PIC16F648A
EEADR: Set to ‘1’ specifies top 128 locations (128-255) of EEPROM Read/Write Operation

bit 6-0 **EEADR**: Specifies one of 128 locations of EEPROM Read/Write Operation

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

TABLE 14-8: SUMMARY OF INTERRUPT REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other Resets(1)
0Bh, 8Bh, 10Bh, 18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	EEIF	CMIF	RCIF	TXIF	—	CCP1IF	TMR2IF	TMR1IF	0000 -000	0000 -000
8Ch	PIE1	EEIE	CMIE	RCIE	TXIE	—	CCP1IE	TMR2IE	TMR1IE	0000 -000	0000 -000

Note 1: Other (non Power-up) Resets include $\overline{\text{MCLR}}$ Reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

14.6 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (e.g., W register and Status register). This must be implemented in software.

Example 14-1 stores and restores the Status and W registers. The user register, W_TEMP, must be defined in a common memory location (i.e., W_TEMP is defined at 0x70 in Bank 0 and is therefore, accessible at 0xF0, 0x170 and 0x1F0). The Example 14-1:

- Stores the W register
- Stores the Status register
- Executes the ISR code
- Restores the Status (and bank select bit register)
- Restores the W register

EXAMPLE 14-1: SAVING THE STATUS AND W REGISTERS IN RAM

```
MOVWF   W_TEMP      ;copy W to temp register,
                    ;could be in any bank
SWAPF   STATUS,W    ;swap status to be saved
                    ;into W
BCF     STATUS,RP0  ;change to bank 0
                    ;regardless of current
                    ;bank
MOVWF   STATUS_TEMP;save status to bank 0
                    ;register
    :
    :(ISR)
    :

SWAPF   STATUS_TEMP,W;swap STATUS_TEMP
register
                    ;into W, sets bank to
original
                    ;state
MOVWF   STATUS      ;move W into STATUS
                    ;register
SWAPF   W_TEMP,F    ;swap W_TEMP
SWAPF   W_TEMP,W    ;swap W_TEMP into W
```

14.7 Watchdog Timer (WDT)

The Watchdog Timer is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the CLKIN pin. That means that the WDT will run, even if the clock on the OSC1 and OSC2 pins of the device has been stopped, for example, by execution of a SLEEP instruction. During normal operation, a WDT time out generates a device Reset. If the device is in Sleep mode, a WDT time out causes the device to wake-up and continue with normal operation. The WDT can be permanently disabled by programming the configuration bit WDTE as clear (**Section 14.1 "Configuration Bits"**).

14.7.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms (with no prescaler). The time-out periods vary with temperature, VDD and process variations from part to part (see DC Specifications, Table 17-7). If longer time-out periods are desired, a postscaler with a division ratio of up to 1:128 can be assigned to the WDT under software control by writing to the OPTION register. Thus, time-out periods up to 2.3 seconds can be realized.

The CLRWDT and SLEEP instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device Reset.

The $\overline{\text{TO}}$ bit in the Status register will be cleared upon a Watchdog Timer time out.

14.7.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken in account that under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler) it may take several seconds before a WDT time out occurs.

CLRW **Clear W**

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W)
1 → Z

Status Affected: Z

Encoding:

00	0001	0000	0011

Description: W register is cleared. Zero bit (Z) is set.

Words: 1

Cycles: 1

Example
```
CLRW
```
Before Instruction
W = 0x5A
After Instruction
W = 0x00
Z = 1

CLRWDT **Clear Watchdog Timer**

Syntax: [*label*] CLRWDT

Operands: None

Operation: 00h → WDT
0 → WDT prescaler,
1 → $\overline{TO}$
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0100

Description: CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

Words: 1

Cycles: 1

Example
```
CLRWDT
```
Before Instruction
WDT counter = ?
After Instruction
WDT counter = 0x00
WDT prescaler = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

COMF **Complement f**

Syntax: [*label*] COMF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: ($\bar{f}$) → (dest)

Status Affected: Z

Encoding:

00	1001	dfff	ffff

Description: The contents of register 'f' are complemented. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
COMF    REG1, 0
```
Before Instruction
REG1 = 0x13
After Instruction
REG1 = 0x13
W = 0xEC

DECF **Decrement f**

Syntax: [*label*] DECF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: (f) - 1 → (dest)

Status Affected: Z

Encoding:

00	0011	dfff	ffff

Description: Decrement register 'f'. If 'd' is '0'. the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
DECF    CNT, 1
```
Before Instruction
CNT = 0x01
Z = 0
After Instruction
CNT = 0x00
Z = 1

INCF **Increment f**

Syntax: [*label*] INCF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) + 1 → (dest)

Status Affected: Z

Encoding:

00	1010	dfff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.

Words: 1

Cycles: 1

Example

```
INCF    REG1, 1
```

Before Instruction
REG1 = 0xFF
Z = 0
After Instruction
REG1 = 0x00
Z = 1

INCFSZ **Increment f, Skip if 0**

Syntax: [*label*] INCFSZ f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) + 1 → (dest), skip if result = 0

Status Affected: None

Encoding:

00	1111	dfff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.
If the result is '0', the next instruction, which is already fetched, is discarded. A NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example

```
HERE     INCFSZ    REG1, 1
         GOTO      LOOP
CONTINUE •
         •
         •
```

Before Instruction
PC = address HERE
After Instruction
REG1 = REG1 + 1
if CNT = 0,
PC = address CONTINUE
if REG1≠ 0,
PC = address HERE +1

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (dest)

Status Affected: C, DC, Z

Encoding:

00	0010	dfff	ffff

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example 1:
```
SUBWF   REG1, 1
```
Before Instruction
REG1 = 3
W = 2
C = ?
After Instruction
REG1 = 1
W = 2
C = 1; result is positive
DC = 1
Z = 0

Example 2: Before Instruction
REG1 = 2
W = 2
C = ?
After Instruction
REG1 = 0
W = 2
C = 1; result is zero
Z = DC = 1

Example 3: Before Instruction
REG1 = 1
W = 2
C = ?
After Instruction
REG1 = 0xFF
W = 2
C = 0; result is negative
Z = DC = 0

SWAPF **Swap Nibbles in f**

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<3:0>) → (dest<7:4>),
(f<7:4>) → (dest<3:0>)

Status Affected: None

Encoding:

00	1110	dfff	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is '0', the result is placed in W register. If 'd' is '1', the result is placed in register 'f'.

Words: 1

Cycles: 1

Example
```
SWAPF   REG1, 0
```
Before Instruction
REG1 = 0xA5
After Instruction
REG1 = 0xA5
W = 0x5A

TRIS **Load TRIS Register**

Syntax: [*label*] TRIS f

Operands: $5 \le f \le 7$

Operation: (W) → TRIS register f;

Status Affected: None

Encoding:

00	0000	0110	0fff

Description: The instruction is supported for code compatibility with the PIC16C5X products. Since TRIS registers are readable and writable, the user can directly address them.

Words: 1

Cycles: 1

Example

To maintain upward compatibility with future PIC® MCU products, do not use this instruction.

TABLE 17-2: COMPARATOR SPECIFICATIONS

Operating Conditions: 2.0V < VDD <5.5V, -40°C < TA < +125°C, unless otherwise stated.							
Param No.	**Characteristics**	**Sym**	**Min**	**Typ**	**Max**	**Units**	**Comments**
D300	Input Offset Voltage	VIOFF	—	±5.0	±10	mV	
D301	Input Common Mode Voltage	VICM	0	—	VDD – 1.5*	V	
D302	Common Mode Rejection Ratio	CMRR	55*	—	—	db	
D303	Response Time(1)	TRESP	— — —	300 400 400	400* 600* 600*	ns ns ns	VDD = 3.0V to 5.5V -40° to +85°C VDD = 3.0V to 5.5V -85° to +125°C VDD = 2.0V to 3.0V -40° to +85°C
D304	Comparator Mode Change to Output Valid	TMC2OV	—	300	10*	µs	

* These parameters are characterized but not tested.

Note 1: Response time measured with one comparator input at (VDD – 1.5)/2, while the other input transitions from VSS to VDD.

TABLE 17-3: VOLTAGE REFERENCE SPECIFICATIONS

Operating Conditions: 2.0V < VDD < 5.5V, -40°C < TA < +125°C, unless otherwise stated.							
Spec No.	**Characteristics**	**Sym**	**Min**	**Typ**	**Max**	**Units**	**Comments**
D310	Resolution	VRES	—	—	VDD/24 VDD/32	LSb LSb	Low Range (VRR = 1) High Range (VRR = 0)
D311	Absolute Accuracy	VRAA	— —	— —	1/4(2)* 1/2(2)*	LSb LSb	Low Range (VRR = 1) High Range (VRR = 0)
D312	Unit Resistor Value (R)	VRUR	—	2k*	—	Ω	
D313	Settling Time(1)	TSET	—	—	10*	µs	

* These parameters are characterized but not tested.

Note 1: Settling time measured while VRR = 1 and VR<3:0> transitions from '0000' to '1111'.

2: When VDD is between 2.0V and 3.0V, the VREF output voltage levels on RA2 described by the equation:[VDD/2 ± (3 – VDD)/2] may cause the Absolute Accuracy (VRAA) of the VREF output signal on RA2 to be greater than the stated max.

TABLE 17-6: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units
10	TosH2ckL	OSC1↑ to CLKOUT↓	PIC16F62XA	—	75	200*	ns
10A			PIC16LF62XA	—	—	400*	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑	PIC16F62XA	—	75	200*	ns
11A			PIC16LF62XA	—	—	400*	ns
12	TckR	CLKOUT rise time	PIC16F62XA	—	35	100*	ns
12A			PIC16LF62XA	—	—	200*	ns
13	TckF	CLKOUT fall time	PIC16F62XA	—	35	100*	ns
13A			PIC16LF62XA	—	—	200*	ns
14	TckL2ioV	CLKOUT ↓ to Port out valid		—	—	20*	ns
15	TioV2ckH	Port in valid before CLKOUT ↑	PIC16F62XA	Tosc+200 ns*	—	—	ns
			PIC16LF62XA	Tosc+400 ns*	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT ↑		0	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to	PIC16F62XA	—	50	150*	ns
		Port out valid	PIC16LF62XA	—	—	300*	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)		100* 200*	—	—	ns

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 17-6: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

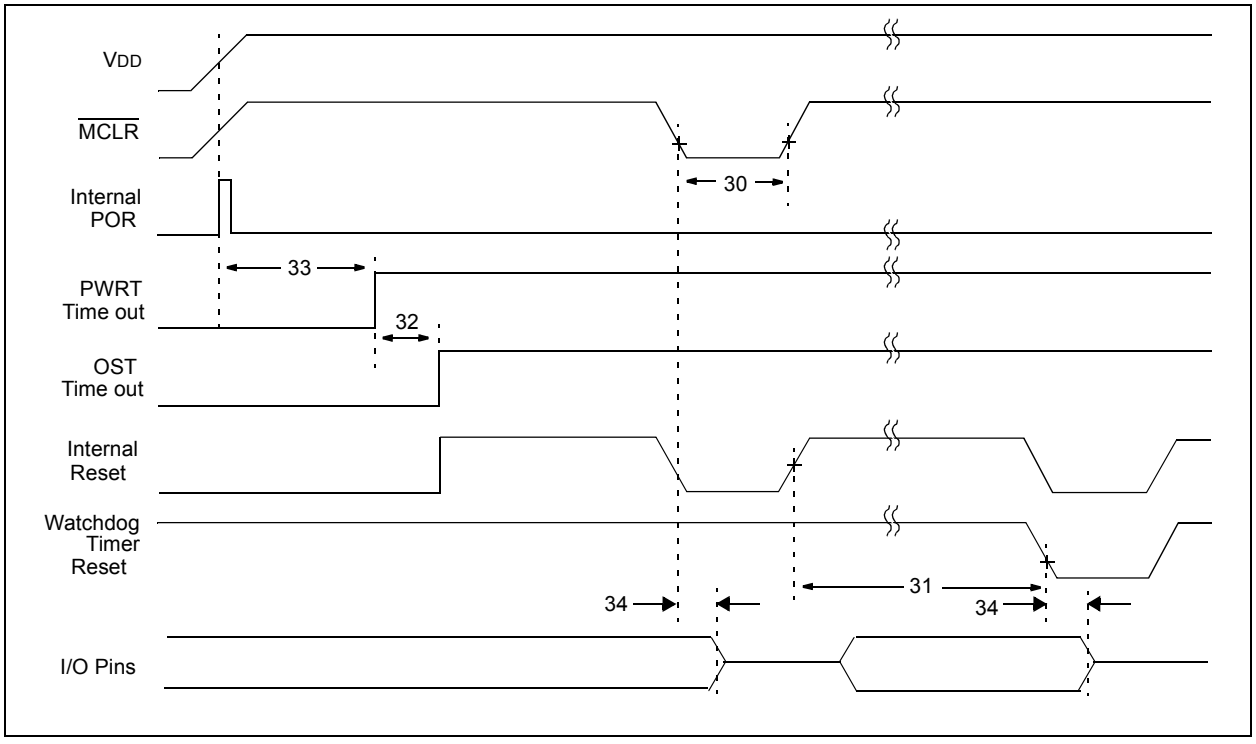
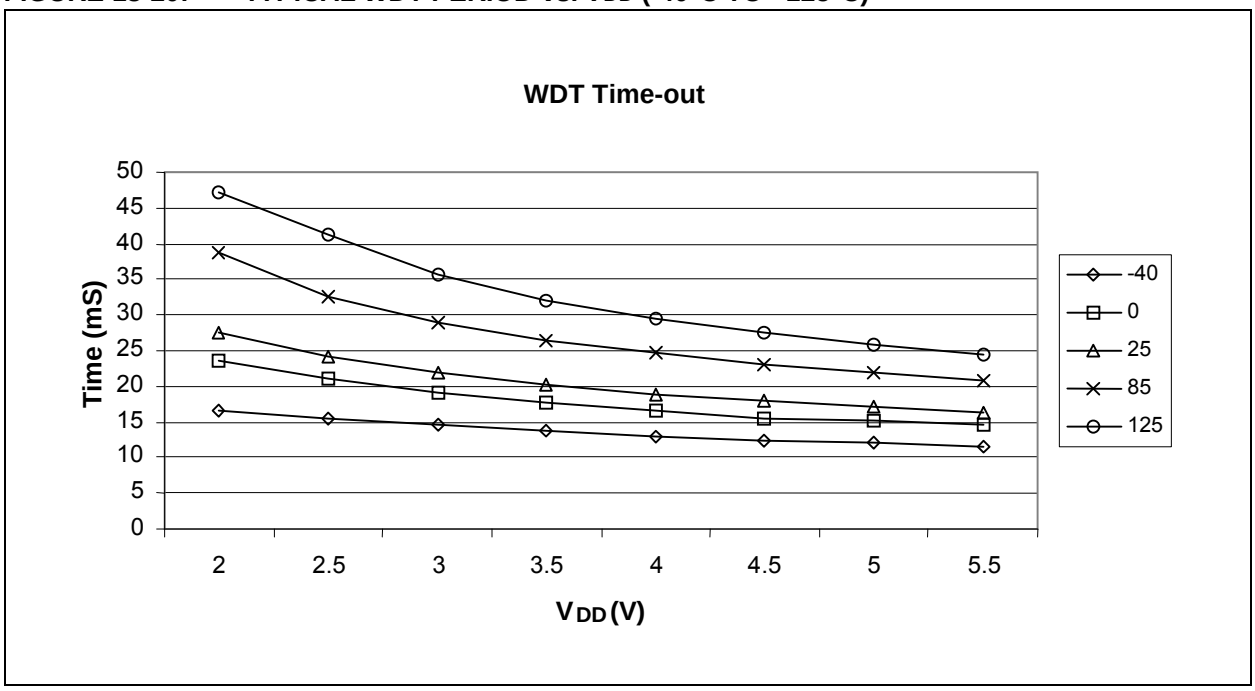
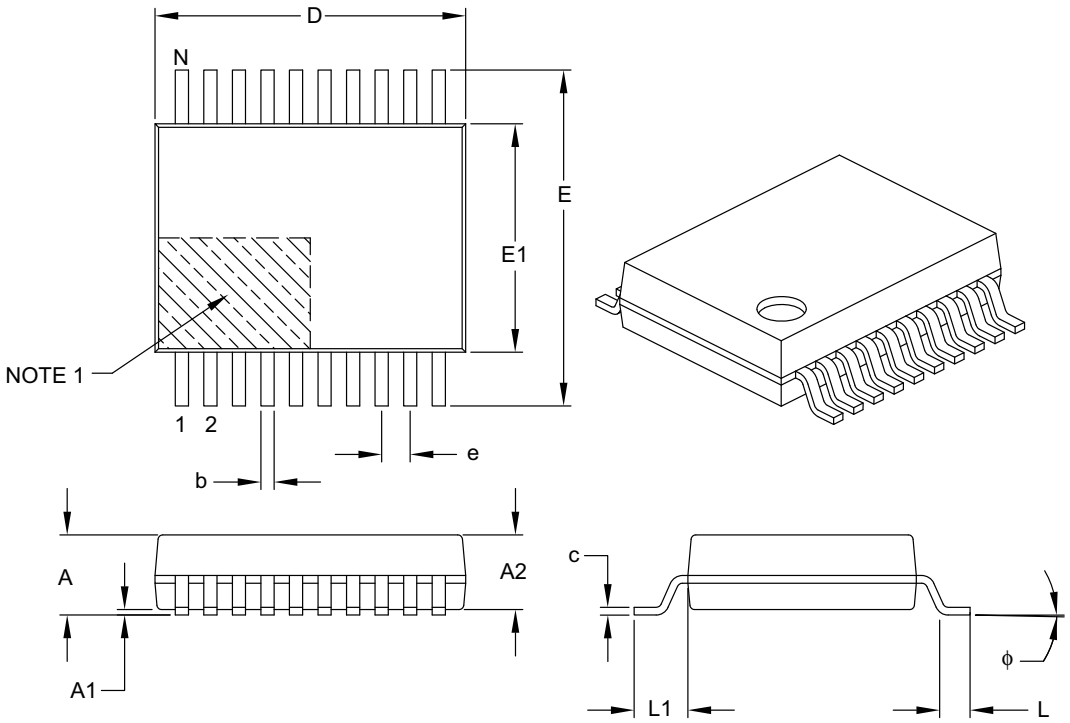


FIGURE 18-20: TYPICAL WDT PERIOD vs. V_{DD} (-40°C TO +125°C)



20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B

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